PRESS RELEASE

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High-Density RDL Interposer Trends and Growth: Will Panel Level Packaging Meet the Need?

Adoption of high-density redistribution layer (RDL) interposers is being driven by high-performance computing, including AI training and inferencing modules, server CPUs, and high-end network switch applications. TechSearch International's latest Advanced Packaging Update report provides an analysis of the RDL interposer market with projections in units and 300mm-wafer format. Trends in panel level packaging (PLP) are discussed along with drivers, options, and panel sizes. High-density PLP capacity by panel size is provided. Challenges for PLP production are described. Suppliers for RDL interposers in wafer and panel format are identified.

An update on data center financing, pushback, and pause after the U.S. midterm elections is provided. Growth projections for AI training and inferencing hardware are presented and shortages of build-up substrates and of materials such as glass fiber for substrate cores are documented. Despite customer-financed capacity expansions, shortages remain. The use of bridges with organic substrates, including options from Intel and IBM, are discussed. Applications and an analysis of supply and demand are provided.

The report examines memory shortages and their impact on the electronics industry. Demand for high bandwidth memory (HBM) is documented, with projections of demand for HBM stacks, DRAM die, and wafers. New memory products are discussed, including high-bandwidth flash (HBF).

TechSearch International's analysis of OSAT financials for the first half of the year is included, with revenue projections for the remainder of the year. The Update is a 45-page report with full references and a set of 75 PowerPoint slides.

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